



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPTG018N10NM5	Issued	18. August 2021
MA#	MA005432189		
Package	PG-HSOG-8-1	Weight*	707.24 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.694	0.81	0.81	8052	8052
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57	
	non noble metal	iron	7439-89-6	0.134	0.02		190	
	non noble metal	copper	7440-50-8	134.219	18.98	19.01	189779	190026
wire	non noble metal	aluminium	7429-90-5	19.598	2.77	2.77	27710	27710
encapsulation	inorganic material	zinc oxide	1314-13-2	2.582	0.36		3650	
	miscellaneous	miscellaneous	-	10.327	1.46		14602	
	plastics	epoxy resin	-	38.726	5.48		54757	
	inorganic material	silicon dioxide	60676-86-0	206.541	29.20	36.50	292037	365046
lead finish	non noble metal	tin	7440-31-5	8.309	1.17	1.17	11749	11749
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	310	311
solder	non noble metal	tin	7440-31-5	0.096	0.01		135	
	noble metal	silver	7440-22-4	0.120	0.02		169	
	non noble metal	lead	7439-92-1	4.571	0.65	0.68	6463	6767
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		117	
	non noble metal	iron	7439-89-6	0.276	0.04		390	
	non noble metal	copper	7440-50-8	275.705	38.98	39.03	389832	390339
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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